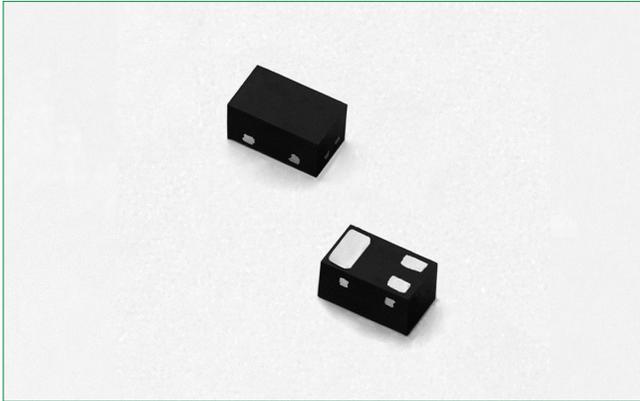


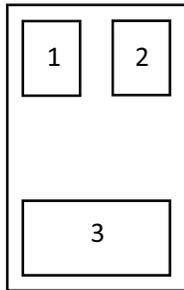
# SC3402-02ETG

5 V, 0.4 pF, 15 kV, SOD883, Ultra Low Capacitance ESD protection

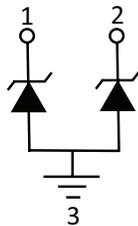
HF  



Pinout



Functional Block Diagram



## Description

The SC3402-02ETG provides ultra-low capacitance, unidirectional and a high level of protection for 2-channel electronic equipment that may experience destructive electrostatic discharges (ESD). The typical capacitance of 0.4 pF helps ensure excellent signal integrity on the most challenging consumer electronics interfaces, such as High-Definition Multimedia Interface (HDMI) and DisplayPort interfaces, and USB 3.0/3.1 Gen 1.

It can safely absorb repetitive ESD strikes at  $\pm 15$  kV (contact discharge, IEC 61000-4-2) without performance degradation and safely dissipate 7 A of 8/20  $\mu$ s surge current (IEC 61000-4-5 2nd edition).

## Features

- ESD, IEC 61000-4-2,  $\pm 15$  kV contact,  $\pm 20$  kV air
- EFT, IEC 61000-4-4, 40 A (5/50 ns)
- Maximum surge tolerance, IEC 61000-4-5 2<sup>nd</sup> edition, 7 A (8/20  $\mu$ s)
- Low leakage current of 100 nA (Max) at 5 V
- Ultra low capacitance of 0.4 pF (Typ @  $V_R = 0$  V)
- Tiny SOD883 package saves board space
- Halogen free, lead free and RoHS compliant
- Moisture sensitivity level (MSL-1)

## Applications

- USB 2.0/3.0
- USB 3.1 Gen 1
- HDMI
- DisplayPort interfaces

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## Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p = 8/20 \mu s$ )	7	A
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

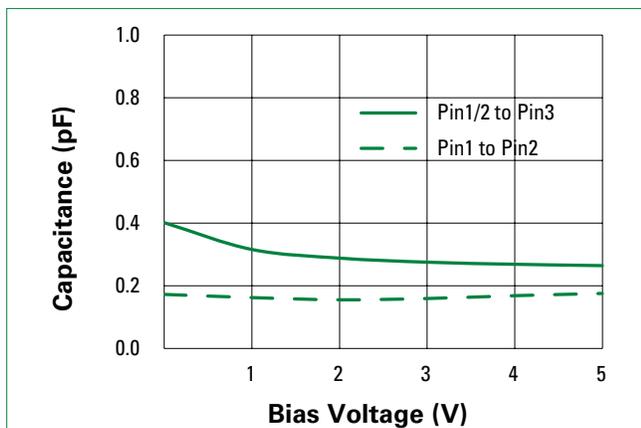
## Electrical Characteristics ( $T_{OP}=25^\circ C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$				5	V
Breakdown Voltage	$V_{BR}$	$I_R = 1 \text{ mA}$	6.5		9.4	V
Reverse Leakage Current	$I_{LEAK}$	$V_R = 5 \text{ V}$		1	100	nA
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP} = 16 \text{ A}$ , $t_p = 0.2/100 \text{ ns}$ (TLP), Pin1/2 to Pin3		4.5		V
		$I_{PP} = 1 \text{ A}$ , $t_p = 8/20 \mu s$ , Pin1/2 to Pin3		2.5		V
		$I_{PP} = 7 \text{ A}$ , $t_p = 8/20 \mu s$ , Pin1/2 to Pin3		4.0		V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p = 100 \text{ ns}$ , Pin1/2 to Pin3		0.17		$\Omega$
ESD Withstand Voltage <sup>1,3</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 15$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 20$			kV
Diode Capacitance <sup>1</sup>	$C_{IO-GND}$	Reverse Bias = 0 V, $f = 1 \text{ MHz}$ , Pin1/2 to Pin3		0.40		pF
	$C_{IO-IO}$	Reverse Bias = 0 V, $f = 1 \text{ MHz}$ , Pin1 to Pin2		0.16		pF

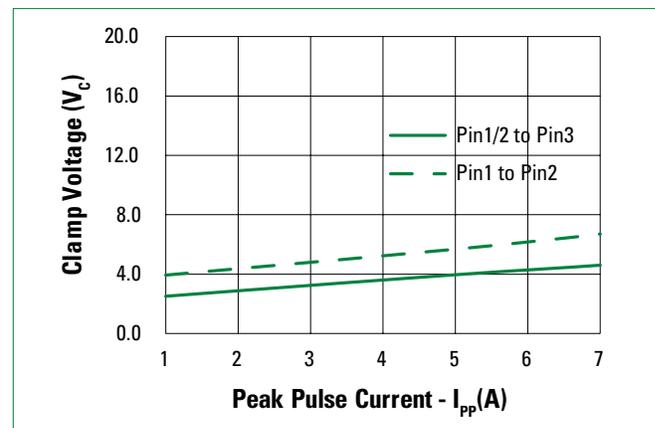
**Note:**

- Parameter is guaranteed by design and/or component characterization
- Transmission Line Pulse (TLP) with 100ns width, 0.2 ns rise time, and average window  $t_1 = 70 \text{ ns}$  to  $t_2 = 90 \text{ ns}$
- Device stressed with ten non-repetitive ESD pulses according to IEC61000-4-2 ( $R = 330 \Omega$ ,  $C = 150 \text{ pF}$ ).

### Capacitance vs. Reverse Bias



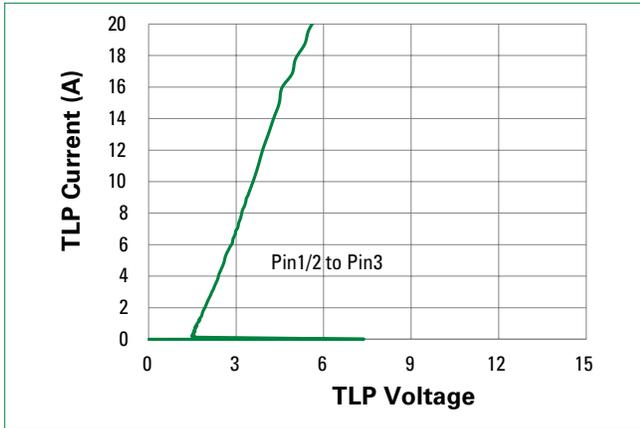
### Clamping Voltage vs $I_{PP}$



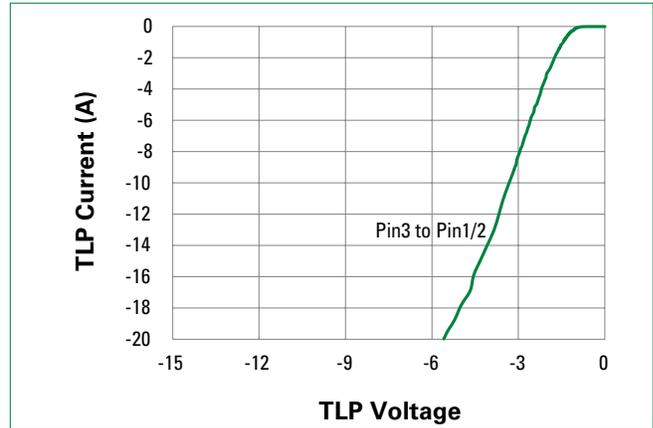
# SC3402-02ETG

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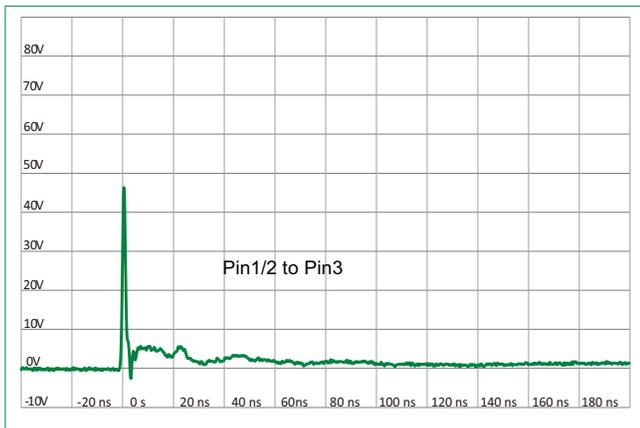
Positive Transmission Line Pulsing (TLP) Plot



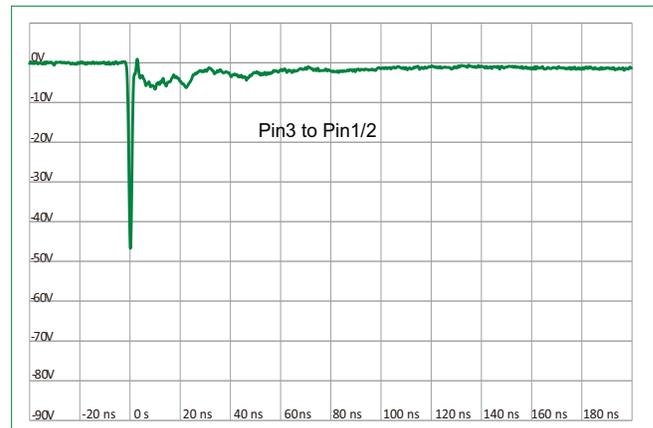
Negative Transmission Line Pulsing (TLP) Plot



IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage



IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage

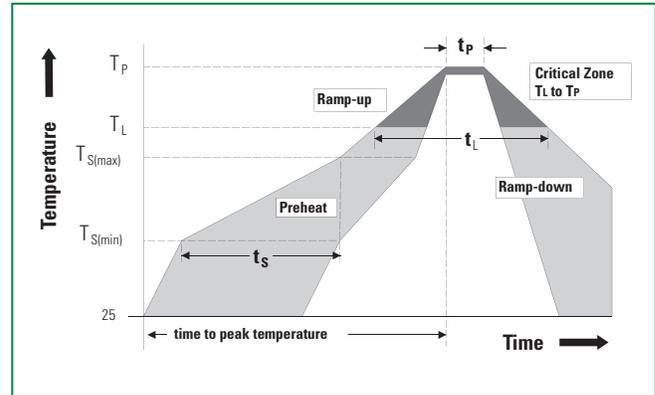


# SC3402-02ETG

5 V, 0.4 pF, 15 kV, SOD883, Ultra Low Capacitance ESD protection

## Soldering Parameters

<b>Reflow Condition</b>		Pb-free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150 °C
	- Temperature Max ( $T_{s(max)}$ )	200 °C
	- Time (min to max) ( $t_s$ )	60 – 120 seconds
<b>Average Ramp Up Rate (Liquidus) Temp (<math>T_L</math>) to Peak</b>		3 °C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3 °C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time Within 5°C of Actual Peak Temperature (<math>t_p</math>)</b>		30 seconds
<b>Ramp-down Rate</b>		6 °C/second max
<b>Time 25°C to Peak Temperature (<math>T_p</math>)</b>		8 minutes max
<b>Do Not Exceed</b>		260 °C



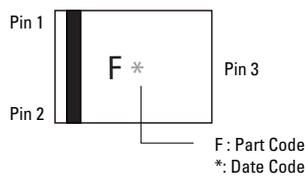
## Ordering Information

Part Number	Package	Min. Order Qty.
SC3402-02ETG	SOD883	10000

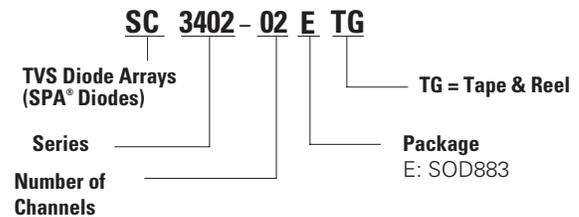
## Product Characteristics

<b>Lead Plating</b>	Pre-plated frame
<b>Lead Material</b>	Copper alloy
<b>Body Material</b>	Molded compound
<b>Flammability</b>	UL recognized compound meeting flammability rating V-0

## Part Marking System

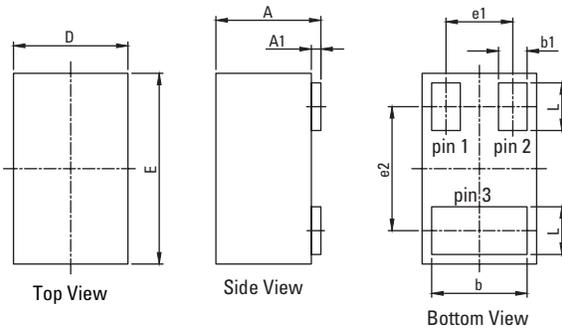


## Part Numbering System

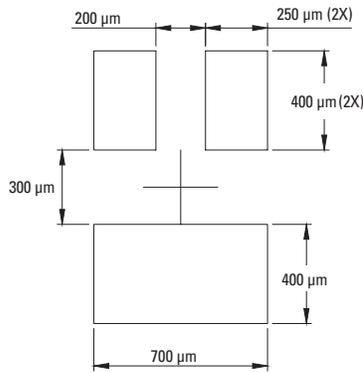


**SC3402-02ETG**

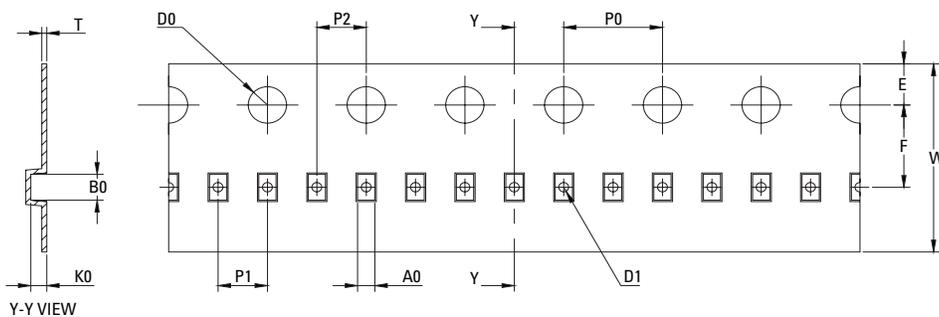
5 V, 0.4 pF, 15 kV, SOD883, Ultra Low Capacitance ESD protection

**Package Dimensions – SOD883**

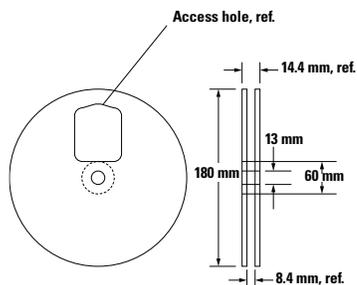
Symbol	Millimeters		
	Min	Nom	Max
A	0.45	0.50	0.55
A1	-	0.02	0.05
D	0.55	0.60	0.65
E	0.95	1.00	1.05
b	0.45	0.50	0.55
b1	0.10	0.15	0.20
L	0.20	0.25	0.30
e1	0.35 BSC		
e2	0.65 BSC		



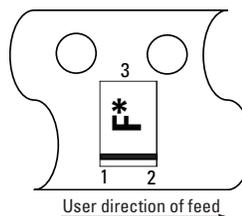
Recommended Soldering pad layout

**Embossed Carrier Tape & Reel Specification – SOD883**

Symbol	Millimeters		
	Min	Nom	Max
A0	0.63	0.70	0.77
B0	1.06	1.12	1.18
D0	1.50	1.55	1.60
D1	0.30	0.45	0.60
E	1.65	1.75	1.85
F	3.40	3.50	3.60
K0	0.54	0.60	0.66
P0	3.90	4.00	4.10
P1	1.90	2.00	2.10
P2	1.95	2.00	2.05
T	0.15	0.20	0.25
W	7.80	8.00	8.30



Component Orientation in Tape



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